

In the claims:

Claims 1-21 were examined.

Claim 3 was cancelled

Amend claims 1-2, 4-6, 8-10 and 13-21 as follows:

1. (currently amended) An apparatus ~~for~~ to apply a selected masking pattern ~~to a workpiece coated with a photosensitive photoresist layer~~ on a workpiece to prevent exposure of select masked regions of the photosensitive photoresist layer, comprising:

a workpiece pre-aligner ~~for~~ disposed to movably supporting support and aligning initially align the workpiece;

a rotation device to engage the workpiece and to rotate the workpiece while being masked; and

an ink delivery device disposed to be arranged to be in communication with the photosensitive photoresist layer of the workpiece ~~for providing a masking pattern of to~~ apply opaque ink to form the selected masking pattern on a photosensitive the photoresist layer in cooperation with the workpiece pre-aligner as the workpiece is rotated;

wherein the opaque ink is opaque to a wavelength of radiation that will activate the photoresist layer on the workpiece.

2. (currently amended) An apparatus according to claim 1 further comprising ~~, wherein the ink delivery device is connected to~~ a control unit in communication with the workpiece pre-aligner, the rotation device and the ink delivery device to control that controls the deposition application of ink onto the photosensitive photoresist layer in the selected masking pattern.

3. (cancelled)

4. (currently amended) An apparatus according to claim 1, wherein the workpiece pre-aligner includes a movable arm ~~capable of engaging and supporting~~ disposed to engage and support the workpiece, wherein the movable arm is in operative communication with a workpiece stage of a lithography tool.

5. (currently amended) An apparatus according to claim 1, wherein the ~~photosensitive~~ photoresist layer is a negative- tone dry film resist.

6. (currently amended) An apparatus according to claim 2, wherein the ~~control unit is connected to the~~ workpiece pre-aligner ~~so that provides~~ information about the ~~workpiece~~ state of the workpiece ~~can be provided~~ to the control unit .

7. (original) An apparatus according to claim 6, wherein the control unit is connected to a main controller of a lithography system.

8. (currently amended) An apparatus according to claim 1, wherein the workpiece pre-aligner is ~~part a component~~ of a lithography tool.

9. (currently amended) An apparatus according to claim 1, wherein the ink delivery device delivers fast-drying ink that adheres to ~~MYLAR®~~ polyethylene terephthalate polyester.

10. (currently amended) An apparatus according to claim 1, wherein the ink delivery device is ~~movable~~ disposed to be moved over the workpiece.

11. (original) An apparatus according to claim 2, wherein the controller is programmable ~~so as to form a desired~~ to control the execution of the selected masking pattern on the ~~workpiece~~ photoresist layer of the workpiece.

12. (original) An apparatus according to claim 1, wherein the ink delivery device includes an inkjet head.

13. (currently amended) A method ~~[[of]]~~ for selectively masking a photosensitive-workpiece photoresist layer on a workpiece, the method comprising the steps of:

selecting one or more regions of the photosensitive-workpiece surface photoresist layer on the workpiece that are to remain-unexposed be masked;

rotating the workpiece during masking; and

masking the one or more select ~~selected~~ regions of the photoresist layer of the workpiece, while the workpiece is rotated, with a layer of ink that is opaque to a wavelength of radiation that ~~activates~~ will activate the photosensitive-workpiece photoresist layer on the workpiece.

14. (currently amended) A method according to claim 13, wherein the masking step includes the step of depositing the layer of ink with an inkjet head.

15. (currently amended) A method according to claim 14, further includes the step of including programming an inkjet head control unit connected to the inkjet head to control the deposition of the layer of ink.

16. (currently amended) A method according to claim 15, wherein the method further includes the step of including coordinating the deposition of the layer of ink with the movement of the workpiece.

17. (currently amended) A method according to claim 14, wherein the masking step ~~the-workpiece~~ includes the step of moving the workpiece and inkjet head relative to each other with the wafer underneath the inkjet head.

18. (currently amended) A method according to claim 13 wherein the workpiece is substantially round ~~and has~~ having an edge, and the one or more ~~select~~ selected regions ~~include~~ includes a narrow annulus adjacent the workpiece edge.

19. (currently amended) A method according to claim 13, wherein the masking step includes the step of forming one or more alphanumeric characters.

20. (currently amended) A method according to claim 13, wherein the masking step includes the step of forming a bar code.

21. (currently amended) A method according to claim 13, wherein the ~~masking is formed~~ the one or more selected regions are outside of an area of the workpiece where exposure fields are to be formed on the workpiece.